PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Xusheng Bao	12/05/2011
Ma Phoo Pwint Hlaing	12/05/2011
Jian Zuo	12/05/2011

RECEIVING PARTY DATA

Name:	STATS ChipPAC, Ltd.
Street Address:	10 Ang Mo Kio Street 65
Internal Address:	#05-17/20 Techpoint
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	569059

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13312730

CORRESPONDENCE DATA

Fax Number:	(480)499-9456
Phone:	480-499-9400
Email:	main@plgaz.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.

Correspondent Name:	PATENT LAW GROUP
Address Line 1:	605 W. Knox Road
Address Line 2:	Suite 104
Address Line 4:	Tempe, ARIZONA 85284

ATTORNEY DOCKET NUMBER:	2515.0377
NAME OF SUBMITTER:	Robert D. Atkins

Total Attachments: 3
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source=ASSIGNMENTS#page2.tif
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OP $40.00 13312730

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, XUSHENG BAO of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled <u>SEMICONDUCTOR DEVICE AND METHOD OF FORMING PATTERNED REPASSIVATION OPENINGS BETWEEN RDL AND UBM TO REDUCE ADVERSE EFFECTS OF ELECTRO-MIGRATION</u>, which is described, illustrated, and claimed in any patent application under Attorney Docket No. <u>2515.0377</u>, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

Signature for XUSHENG BAO

Witnessed on this date: 5 DEC 2011

Signature of Witness:

Printed Name of Witness: DIOSCORO MERILO

Address of Witness: 5 YISHUN STREET 22
SINGAPORE 768442

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, MA PHOO PWINT HLAING of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING PATTERNED REPASSIVATION OPENINGS BETWEEN RDL AND UBM TO REDUCE ADVERSE EFFECTS OF ELECTRO-MIGRATION, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0377, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for MA PHOO PWINT HLAING

Witnessed on this date: 5 DEC. 2011

Signature of Witness:

Printed Name of Witness: DIOSCORO MERILO

Address of Witness: 5 YICHUN STREET 23
SINGAPORE 768442

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, JIAN ZUO of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING PATTERNED REPASSIVATION OPENINGS BETWEEN RDL AND UBM TO REDUCE ADVERSE EFFECTS OF ELECTRO-MIGRATION, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0377, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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